

# TECHNICAL REPORT



**A method of temperature-rise verification of low-voltage switchgear and controlgear assemblies by calculation**

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# TECHNICAL REPORT



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**A method of temperature-rise verification of low-voltage switchgear and controlgear assemblies by calculation**

INTERNATIONAL  
ELECTROTECHNICAL  
COMMISSION

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

**A METHOD OF TEMPERATURE-RISE VERIFICATION OF LOW-VOLTAGE SWITCHGEAR AND CONTROLGEAR ASSEMBLIES BY CALCULATION**

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IEC TR 60890 has been prepared by subcommittee 121B: Low-voltage switchgear and controlgear assemblies, of IEC technical committee 121: Switchgear and controlgear and their assemblies for low-voltage. It is a Technical Report.

This third edition cancels and replaces the second edition published in 2014. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- alignment with IEC 61439-1:2020;
- addition of individual annexes for guidance of technical explanations related to:
  - effect of an uneven power distribution;
  - additional temperature-rise due to solar radiation;
  - effect of different enclosure materials;
  - effect of different natural ventilation management;
  - forced ventilation management;

- power losses calculation;
- impact of an adjacent wall can have on the assembly cooling surface(s);
- maximum internal ambient temperature limit into an assembly;
- validity area of the calculation extended from 3 150 A to 3 200 A;
- addition of an algebraic equation to the different curves included in the document.

The text of this Technical Report is based on the following documents:

Draft	Report on voting
121B/136/DTR	121B/147/RVDTR

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this Technical Report is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at [www.iec.ch/members\\_experts/refdocs](http://www.iec.ch/members_experts/refdocs). The main document types developed by IEC are described in greater detail at [www.iec.ch/publications](http://www.iec.ch/publications).

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- withdrawn,
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- amended.

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## INTRODUCTION

In the series of design verifications of IEC 61439-1 a temperature-rise verification of low-voltage power switchgear and controlgear assemblies is specified. This can be by test, however, alternatives are acceptable under defined circumstances. Selection of the method used for temperature-rise verification is the responsibility of the original manufacturer. Where applicable this document can also be used for temperature-rise verification of similar products in accordance with other standards (e.g. IEC 60204-1). The method of calculation can also be used to determine the thermal power dissipation capability of an enclosure in accordance with IEC 62208 for a given internal air temperature-rise. The factors and coefficients, set out in this document have been derived from measurements on numerous assemblies and the method has been verified by comparison with test results.

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# A METHOD OF TEMPERATURE-RISE VERIFICATION OF LOW-VOLTAGE SWITCHGEAR AND CONTROLGEAR ASSEMBLIES BY CALCULATION

## 1 Scope

This document specifies a method of air temperature-rise calculation inside enclosures for low-voltage switchgear and controlgear assemblies or similar products in accordance with their respective standard.

The method is primarily applicable to enclosed assemblies or partitioned sections of assemblies without forced ventilation. However, some technical guidance to adapt it for the use of forced ventilation is given in this document. The results obtained by using this method are directly influenced by the accuracy of the evaluation of power losses used as inputs to perform the thermal calculations.

NOTE The air temperature within the enclosure is equal to the ambient air temperature outside the enclosure plus the temperature-rise of the air inside the enclosure caused by the power losses of the installed equipment.

For the method to be applied, the maximum daily average ambient air temperature outside the assembly at the place of installation is specified between 10 °C and 50 °C. The maximum daily temperature does not exceed the maximum daily average temperature by more than 5 K.

Several annexes in this document provide guidance on how temperature-rise within assemblies can be affected by influences which are not considered in the calculation method included in this document, for example, when the assembly is subject to solar radiation. In such cases, different means of verification to that given in this document can be applied to ensure a definitive result and verification of the design.

## 2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61439 (all parts), *Low-voltage switchgear and controlgear assemblies*

IEEE C37.24-2017, *IEEE Guide for Evaluating the Effect of Solar Radiation on Outdoor Metal-Enclosed Switchgear*

## 3 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 61439 (all parts) apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at <http://www.electropedia.org/>
- ISO Online browsing platform: available at <http://www.iso.org/obp>

## 4 Verification conditions

When this method of calculation is applied to low-voltage switchgear and controlgear assemblies the following conditions shall be fulfilled:

- the assembly is designed for AC currents and frequencies up to and including 1 600 A, 60 Hz. For higher current ratings or frequencies, the method could be used with additional verifications taking into account the effect of eddy-currents on the temperature distribution inside the assembly as required by the relevant product standards.

NOTE 1 In IEC 61439-2, additional requirements for currents in excess of 1 600 A are specified to take into account the considerably increased power losses due to magnetic effects (eddy currents, proximity effect, skin effect)

- the assembly is designed for DC currents up to and including 3 200 A. For higher current ratings the method could be used with additional verifications as required by the relevant product standards;
- conductors carrying currents in excess of 200 A AC, and the adjacent structural parts are so arranged that eddy-current and hysteresis losses are negligible;
- there is an approximately even distribution of power losses inside the enclosure;
- the power losses data for all built-in components are available or can be calculated (see Clause 5);
- the installed equipment is so arranged that air circulation is not significantly impeded.

NOTE 2 When this method is used to determine the thermal power dissipation capability of an empty enclosure in accordance with IEC 62208, the above conditions do not apply.

## 5 Calculation method

### 5.1 Assumptions made in this calculation

To use the calculation method of this document, the following assumptions are deemed valid:

- the enclosure is made of metal (steel, aluminium, stainless steel) coated (both sides, inside and outside), insulating material like thermoplastic or thermoset or similar (see Annex D);
- the enclosure is made of a single layer material or multiple layers without air-gap;
- for enclosures with or without natural ventilation, there are no more than five horizontal partitions in the assembly or in a section of it;
- the enclosure is designed without ventilation openings or;
- the enclosure is designed with free air inlet and outlet ventilation openings, without the inclusion of any additional filter (see Annex E);
  - the cross-section of the air outlet openings is at least 10 % bigger than that of the inlet openings to permit the chimney effect;
  - the minimum cross section of air inlet openings is 10 cm<sup>2</sup>;

NOTE 1 Figure 3 and the formula given in Table 7 are not usable for lower cross sections. Assemblies with a sum of the air inlet openings less than 10 cm<sup>2</sup> are considered as assemblies without an air inlet.

- if the enclosure has air inlet and outlet openings with filters for an IP5X rating or higher then these openings are not considered for the calculation;
- for IP ratings lower than IP5X the effective free air cross section of the openings shall be used for calculation (see Annex E);
- where enclosures with natural ventilation openings have compartments, the surface of each horizontal partition shall be provided with free air ventilation openings of at least 50 % of the horizontal cross-section of the partition (see Clause B.1);
- power losses are considered as a sum of the followings:
  - power losses of low-voltage switchgear and controlgear (see Clause G.2);

- power losses of conductors connecting low-voltage switchgear and controlgear (see Clause G.3);
  - power losses of busbars (see Clause G.4);
  - power losses of electronic devices (see Clause G.5);
- the enclosure is not subject to solar radiation.

## 5.2 Necessary information

The following data shall be used to calculate the temperature-rise of the air inside an enclosure:

- dimensions of the enclosure: height/width/depth;
- type of installation of the enclosure according to Figure 4;
- design of enclosure, i.e. with or without ventilation openings;
- number of internal horizontal partitions;
- effective power loss of equipment installed in the enclosure, see Annex G;
- effective power loss ( $P_v$ ) of conductors according to Annex I.

## 5.3 Calculation procedure

### 5.3.1 General

For the enclosures specified in columns 4 and 5 of Table 1, the calculation of the temperature-rise of the air inside the enclosure is carried out using the formulae laid down in columns 1 to 3 of Table 1.

The pertinent factors and exponents (characteristics) are obtained from columns 6 to 10 of Table 1.

The symbols, units and designations are stated in Table 2.

For enclosures having more than one section with vertical partitions, the temperature-rise of the air inside the enclosure shall be determined separately for each section.

Where enclosures without vertical partitions or individual sections have an effective cooling surface greater than 11,5 m<sup>2</sup> or a width greater than about 1,5 m, they should be divided for the calculation into fictitious sections, whose dimensions approximate to the foregoing values.

NOTE The template (see Figure 9) can be used as a calculation aid.

### 5.3.2 Determination of the effective cooling surface $A_e$ of the enclosure

The calculation is carried out according to Formula (1) in column 1 of Table 1.

The effective cooling surface  $A_e$  of an enclosure is the sum of the individual surfaces  $A_o$  multiplied by the surface factor  $b$ . This factor takes into account the heat dissipation of the individual surfaces according to the type of installation of the enclosure (see Annex H for additional explanations).

### 5.3.3 Determination of the internal temperature-rise $\Delta t_{0,5}$ of the air at mid-height of the enclosure

The calculation is carried out according to Formula (2) in column 2 of Table 1.

In Formula (2) the enclosure constant  $k$  allows for the size of the effective cooling surface for enclosures without ventilation openings and, in addition, for the cross-section of the air inlet openings for enclosures with ventilation openings.

The dependence of the temperature-rise occurring in the enclosure on the effective power loss  $P$  is expressed by the exponent  $x$ .

The factor  $d$  allows for the dependence of the temperature-rise on the number of internal horizontal partitions.

### 5.3.4 Determination of the internal temperature-rise $\Delta t_{1,0}$ of air at the top of the enclosure

The calculation is made according to Formula (3) in column 3 of Table 1.

Factor  $c$  allows for the temperature distribution inside an enclosure. Its determination varies with the design and installation of the assembly as follows:

- a) For enclosures without ventilation openings and with an effective cooling surface:

$$A_e > 1,25 \text{ m}^2$$

The factor  $c$  from Figure 4, depends on the type of installation and the height/base factor  $f$ , where:

$$f = \frac{h^{1,35}}{A_b}$$

- b) For enclosures with ventilation openings and with an effective cooling surface:

$$A_e > 1,25 \text{ m}^2$$

The factor  $c$  from Figure 6, depends on the cross-section of air inlet openings and the height/base factor  $f$ , where:

$$f = \frac{h^{1,35}}{A_b}$$

- c) For enclosures without ventilation openings and with an effective cooling surface:

$$A_e \leq 1,25 \text{ m}^2$$

The factor  $c$  from Figure 8, depends on the height/width factor  $g$ , where:

$$g = \frac{h}{w}$$

where

$h$  is the enclosure height, in m;

$A_b$  is the surface area of the enclosure base, in  $\text{m}^2$ ;

$w$  is the enclosure width, in m.

### 5.3.5 Characteristic curve for temperature-rise of air inside enclosure

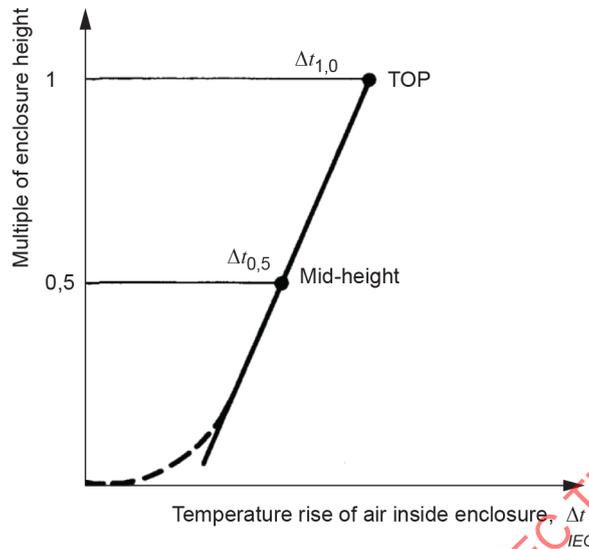
#### 5.3.5.1 General

To evaluate the design according to Clause 7, the calculated results of 5.3.3 and 5.3.4 shall be applied with the proper characteristic curve for temperature-rise of air inside the enclosure as a function of the enclosure height. The air temperatures within horizontal levels are practically constant.

#### 5.3.5.2 Temperature-rise characteristic curve for enclosures with an effective cooling surface $A_e$ exceeding $1,25 \text{ m}^2$

As a general rule, the characteristic curve of temperature-rise is adequately well defined by a straight line which runs through the points  $\Delta t_{1,0}$  and  $\Delta t_{0,5}$  (see Figure 1).

The internal air temperature-rise at the bottom of the enclosure is close to zero, i.e. the characteristic curve flattens out towards zero. In practice, the dotted part of the characteristic curve is of secondary importance.



**Figure 1 – Temperature-rise characteristic curve for enclosures with  $A_e$  exceeding  $1,25 \text{ m}^2$**

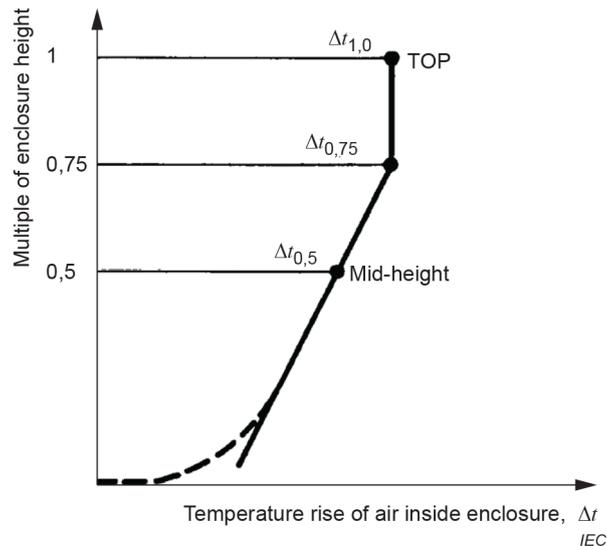
**5.3.5.3 Temperature-rise characteristic curve for enclosures with an effective cooling surface  $A_e$  not exceeding  $1,25 \text{ m}^2$**

For this type of enclosure, the maximum temperature-rise in the upper quarter is constant and the values for  $\Delta t_{1,0}$  and  $\Delta t_{0,75}$  are identical (see Figure 2).

The characteristic curve is obtained by connecting the temperature-rise values at an enclosure level of 0,75 and 0,5 (see Figure 2).

The internal air temperature-rise at the bottom of the enclosure is close to zero, i.e. the characteristic curve flattens out towards zero. In practice, the dotted part of the characteristic curve is of secondary importance.

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**Figure 2 – Temperature-rise characteristic curve for enclosures with  $A_e$  not exceeding 1,25 m<sup>2</sup>**

#### 5.4 Maximum internal air temperature limits

This document contains a method to calculate the internal air temperature within an enclosure. The resulting temperature shall not exceed the maximum absolute temperature allowed by different types of devices and products installed inside.

The user of this document should refer to the manufacturer's instructions regarding the maximum operational temperature allowed for the devices used inside the assembly.

NOTE The value of internal air temperature has a direct influence on the ageing and operation of built-in components.

## 6 Further considerations

### 6.1 General

The means of temperature-rise calculation in this document relate to specific arrangements of assembly in the conditions as defined. These arrangements and conditions do not cover all designs of assembly or the conditions in which some are installed. Where good practises are applied the calculation methods in this document can lead to conservative results.

Annex B, Annex C, Annex D, Annex E, Annex F, Annex H, Annex J and Annex K detail good practice that can lead to an improvement in thermal performance or some aspects not considered in the calculation method in this document. However, when using these additional considerations, to ensure a defined performance of an assembly, further verification, e.g. test, shall be performed.

### 6.2 Guidance on the effects of an uneven power distribution

The aim of Annex B is to determine the temperature-rise where there is not an even power distribution within an assembly using as a starting point the temperature-rise of a reference design or calculation in accordance with Clause 5.

### **6.3 Guidance on the additional temperature-rise effect due to solar radiation**

In case of outdoor assemblies that are subject to direct sunlight, solar irradiance can significantly increase internal air temperature-rise and require a derating of the rated currents of the assembly. See Annex C.

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## 7 Evaluation of the design

It shall be determined whether the equipment within the assembly can operate satisfactorily at the relevant calculated internal air temperature-rise.

If it is not so, the parameters will have to be changed and the calculation repeated.

**Table 1 – Method of calculation, application, formulas and characteristics**

1	2	3		4	5 <sup>a</sup>	6	7	8	9	10	11
		Calculation formulae									
Effective cooling surface $A_e$	Temperature-rise of air		Effective cooling surface $A_e$	Enclosure without ventilation openings	Factors	Exponent	Plotting of temperature-rise characteristics				
	At mid-height of the enclosure	At (internal) top of enclosure						$b$ see	$k$ see	$d$ see	$c$ see
(1) $A_e = \Sigma (A_o \times b)$	(2) $\Delta T_{0,5} = k \times d \times P^x$	(3) $\Delta T_{1,0} = c \times \Delta T_{0,5}$	>1,25 m <sup>2</sup>	Enclosure without ventilation openings	Figure 3	Figure 4	Figure 4	Figure 4	Figure 4	0,804	See 5.3.5.2
			≤1,25 m <sup>2</sup>	Enclosure with ventilation openings	Figure 5	Table 3	Table 5	Figure 6	Figure 6	0,715	
				Enclosure without ventilation openings	Figure 7	$d=1$	Figure 8	Figure 8	Figure 8	0,804	See 5.3.5.3

<sup>a</sup> For enclosure with ventilation openings with effective surface  $A_e \leq 1,25 \text{ m}^2$  the criteria of enclosures without ventilation openings can be used.

For symbols, units and designations, see Table 2.

For method of calculation, see also the examples given in Annex A.

**Table 2 – Symbols, units and designations**

Symbol	Unit	Designation
$A_o$	m <sup>2</sup>	Surfaces of external sides of enclosure
$A_b$	m <sup>2</sup>	Enclosure base surface
$A_e$	m <sup>2</sup>	Effective cooling surface of enclosure
$A_s$	m <sup>2</sup>	Surface area, which can transport heat (usually excluding the bottom area)
$\alpha$	W/m <sup>2</sup> K	Heat transfer coefficient (includes conduction and radiation of heat)
$b$	–	Surface factor
$c$	–	Temperature distribution factor
$c_p$	J/kg*K	Heat capacity (of air)
$d$	–	Temperature-rise factor for internal horizontal partitions inside enclosure
$f$	–	Height/base factor
$g$	–	Height/width factor
$h$	m	Enclosure height
$k$	–	Enclosure constant
$n$	–	Number of internal horizontal partitions (up to five partitions)
$P$	W	Effective power loss of equipment installed inside enclosure (determined according to Annex G)
$P_{890}$	W	Calculated power dissipation of the enclosure according to this document, without considering natural ventilation
$P_{fan}$	W	Power losses dissipated by forced ventilation
$P_v$	W	Effective power losses of conductors
$P_w$	W	Total dissipated power
$\rho$	kg/m <sup>3</sup>	Mass density (of air) at $T_a$
$V$	m <sup>3</sup> /s	Volume flow rate of the air flow through the enclosure
$S_{air}$	cm <sup>2</sup>	Cross-section of air inlet openings
$T_a$	°C	Ambient temperature
$T_{int}$	°C	Temperature inside the enclosure
$T_{int,max}$	°C	Maximum temperature allowed inside the enclosure (limited e.g. by devices)
$w$	m	Enclosure width
$x$	–	Exponent
$\Delta t$	K	Temperature-rise of air inside enclosure in general
$\Delta t_{0,5}$	K	Temperature-rise of air at (internal) mid-height of enclosure
$\Delta t_{0,75}$	K	Temperature-rise of air at (internal) three quarters height of enclosure
$\Delta t_{1,0}$	K	Temperature-rise of air at (internal) top of enclosure

**Table 3 – Surface factor  $b$  according to the type of installation**

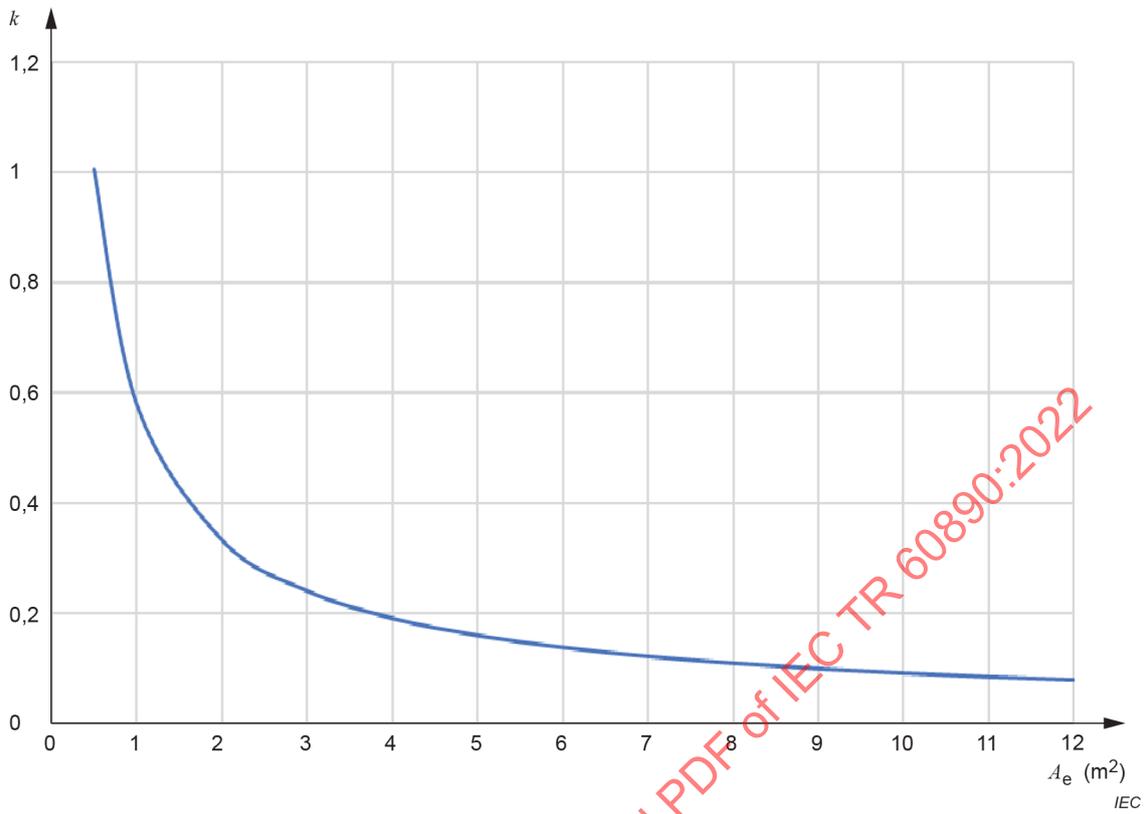
Type of installation	Surface factor $b$
Exposed top surface	1,4
Covered top surface, e.g. of built-in enclosures	0,7
Exposed side faces, e.g. front, rear and side walls	0,9
Covered side faces, e.g. rear side of wall-mounted enclosures	0,5
Side faces of central enclosures	0,5
Floor surface	not taken into account
Fictitious side faces of sections (see 5.3) which have been introduced only for calculation purposes are not taken into account	

**Table 4 – Factor  $d$  for enclosures without ventilation openings and with an effective cooling surface  $A_e > 1,25 \text{ m}^2$** 

Number of horizontal partitions $n$	0	1	2	3	4	5
Factor $d$	1,00	1,05	1,15	1,30	1,45	1,55
NOTE Alternative factor $d$ values than those of Table 4 can be used according to comparison with test results of similar configurations.						

**Table 5 – Factor  $d$  for enclosures with ventilation openings and an effective cooling surface  $A_e > 1,25 \text{ m}^2$** 

Number of horizontal partitions $n$	0	1	2	3	4	5
Factor $d$	1,00	1,05	1,10	1,15	1,2	1,25
NOTE Alternative factor $d$ values than those of Table 5 can be used according to comparison with test results of similar configurations.						



**Key**

$A_e$  effective cooling surface (see 5.3.2)

$k$  enclosure constant (see 5.3.3)

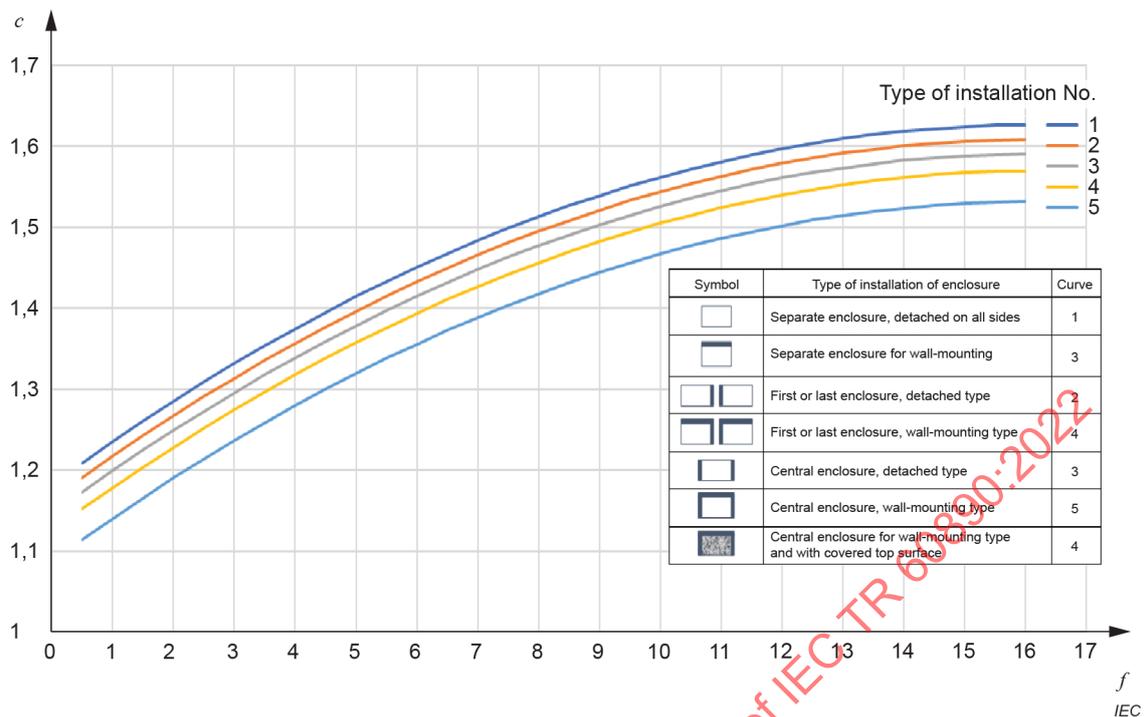
NOTE See Table 6 for the algebraic expression related to the curve.

**Figure 3 – Enclosure constant  $k$  for enclosures without ventilation openings, with an effective cooling surface  $A_e > 1,25 \text{ m}^2$**

Boundary conditions: the factor  $A_e$  shall be higher than 1,25 and not exceed 12.

**Table 6 – Equation for Figure 3**

Variable	Algebraic expression
$k$	$k = 0,58 \times (A_e)^{-0,795}$
<b>Key</b>	
$A_e$ effective cooling surface (m <sup>2</sup> )	
$k$ enclosure constant	

**Key**

$f$  height/base factor (see 5.3.4)

$c$  temperature distribution factor (see Figure 6 and Figure 8)

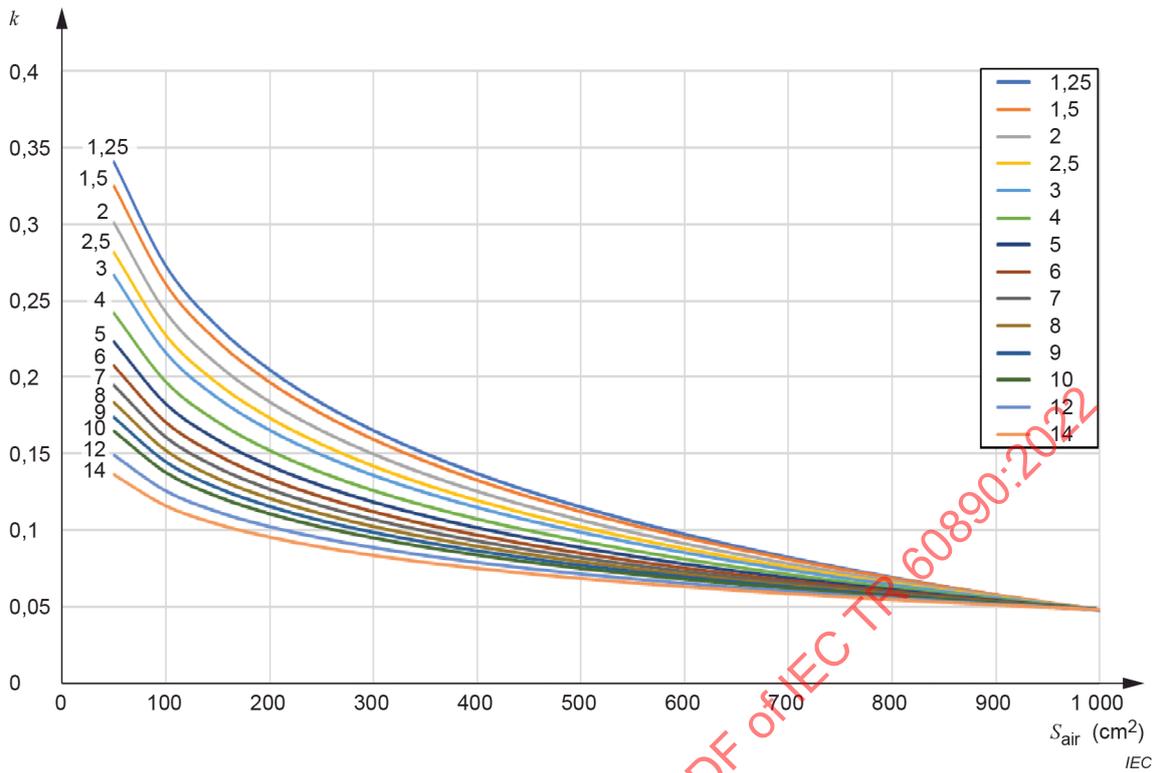
NOTE See Table 7 for the algebraic expressions related to the curves.

Boundary conditions: the factor  $f$  shall be higher than 0,3 and not exceed 16.

**Figure 4 – Temperature distribution factor  $c$  for enclosures without ventilation openings and with an effective cooling surface  $A_e > 1,25 \text{ m}^2$**

**Table 7 – Equations for Figure 4**

Installation type	Algebraic expressions
5	$c = -0,0017 \times f^2 + 0,055 \times f + 1,087$
4	$c = -0,0017 \times f^2 + 0,055 \times f + 1,125$
3	$c = -0,0017 \times f^2 + 0,055 \times f + 1,146$
2	$c = -0,0017 \times f^2 + 0,055 \times f + 1,164$
1	$c = -0,0017 \times f^2 + 0,055 \times f + 1,182$
<b>Key</b>	
$c$ temperature distribution factor	
$f$ height / base factor; $0,3 \leq f \leq 16$ . If $f$ exceeds 16 then $c$ should be calculated with $f$ equal 16.	



**Key**

$S_{air}$  cross-section of the corresponding air outlet openings

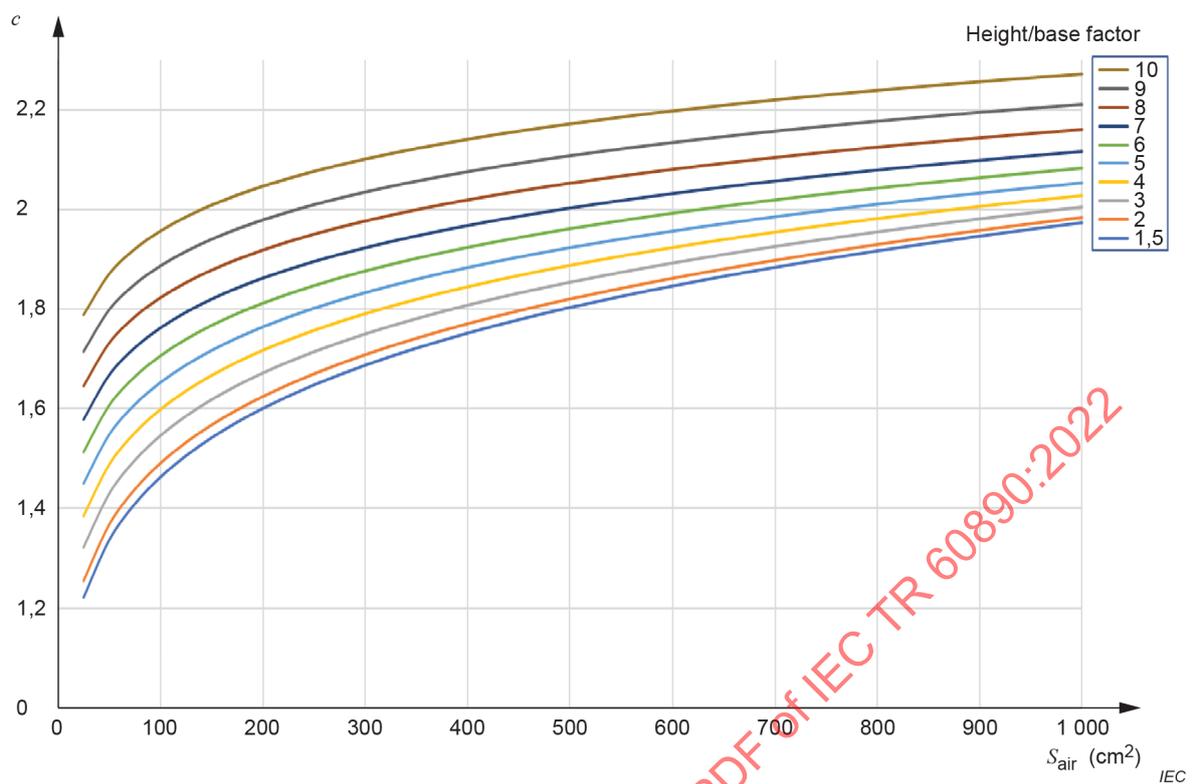
$k$  enclosure constant (see 5.3.3)

Boundary conditions: the factor  $S_{air}$  shall be equal or higher than 10 cm<sup>2</sup> and not exceed 1 000 cm<sup>2</sup>.

**Figure 5 – Enclosure constant  $k$  for enclosures with ventilation openings and an effective cooling surface  $A_e > 1,25$  m<sup>2</sup>**

**Table 8 – Equations for Figure 5**

Variable	Algebraic expressions
$Ak$	$Ak = 2,83 \times 10^{-2} \times \ln(A_e) - 10,39 \times 10^{-2}$
$Bk$	$Bk = 19,52 \times 10^{-2} \times \ln(A_e) - 76,56 \times 10^{-2}$
$k$	$k = Ak \times \ln(S_{air}) - Bk$
<b>Key</b>	
$A_e$	effective cooling surface (m <sup>2</sup> )
$S_{air}$	cross-section of air inlet openings (cm <sup>2</sup> )
$k$	enclosure constant
$Ak$ and $Bk$ are intermediary variables to calculate the enclosure constant $k$ .	

**Key**

$S_{\text{air}}$  cross-section of the corresponding air outlet openings, cross-section of the corresponding air outlet should be at least 1,1 times that of the air inlet openings

$c$  temperature distribution factor

NOTE 1 See Table 9 for the algebraic expressions related to the curves.

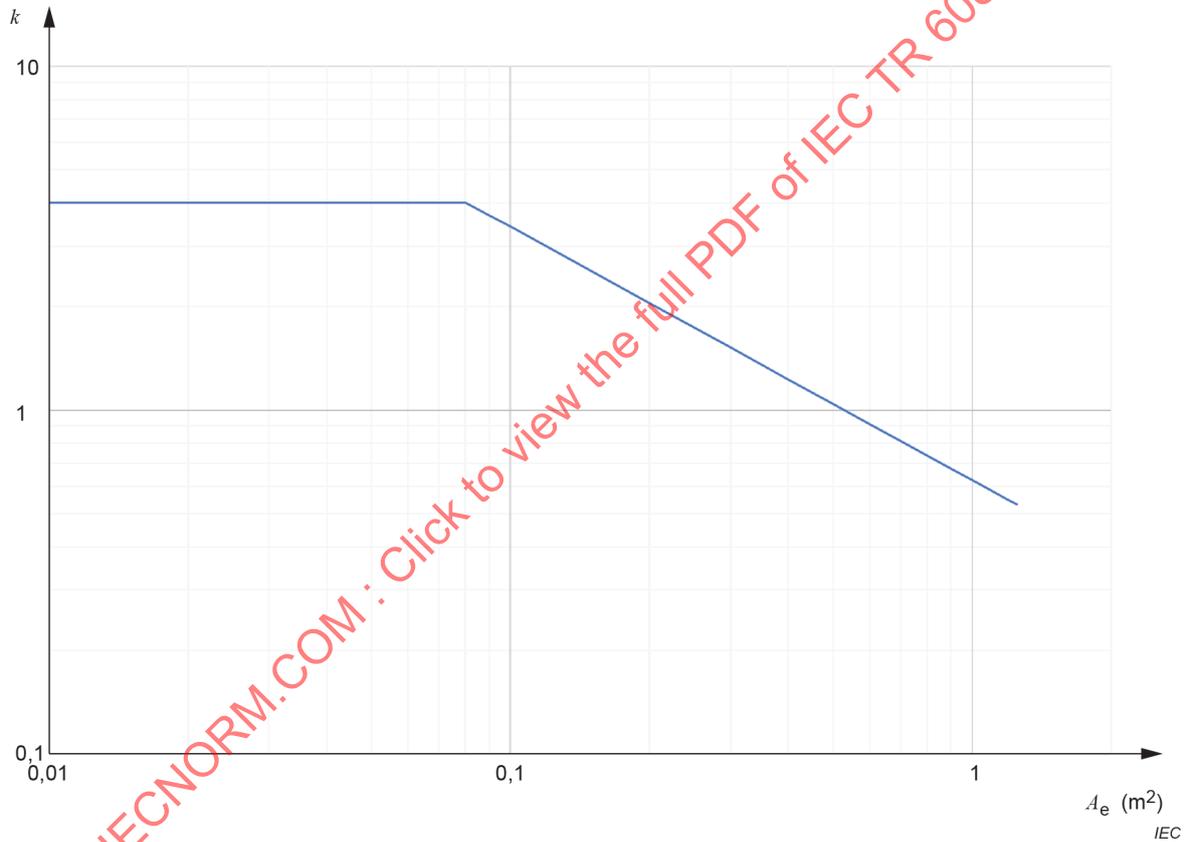
NOTE 2 Height/base factor  $f$ , see 5.3.4.

Boundary conditions: the factor  $S_{\text{air}}$  shall be equal or higher than  $10 \text{ cm}^2$  and not exceeding  $1\,000 \text{ cm}^2$ .

**Figure 6 – Temperature distribution factor  $c$  for enclosures with ventilation openings and an effective cooling surface  $A_e > 1,25 \text{ m}^2$**

**Table 9 – Equations for Figure 6**

Variable	Algebraic expressions
$A_c$	$A_c = 7,6 \times f + 69$
$B_c$	$B_c = 5,1 \times 10^{-4} \times f^2 - 1,35 \times 10^{-2} \times f + 14,931 \times 10^{-2}$
$c$	$c = 0,01 \times A_c \times S_{air} \wedge B_c$
<b>Key</b>	
$c$	temperature distribution factor
$f$	height / base factor
$S_{air}$	cross-section of air inlet opening (cm <sup>2</sup> )
$A_c$ and $B_c$	are intermediary variables to calculate the temperature distribution factor $c$ .



**Key**

$A_e$  effective cooling surface (see 5.3.2)

$k$  enclosure constant (see 5.3.3)

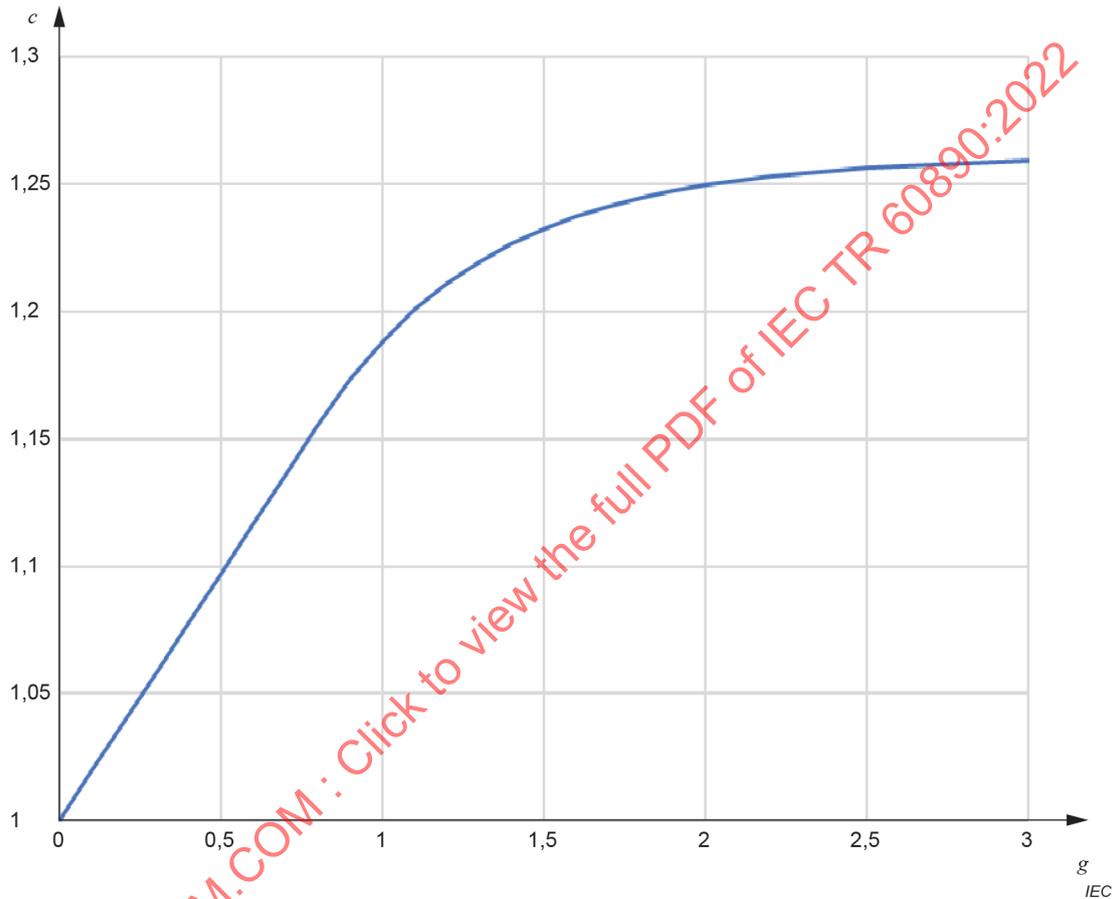
NOTE See Table 10 for the algebraic expression related to the curve.

Boundary conditions: the factor  $A_e$  shall not exceed 1,25.

**Figure 7 – Enclosure constant  $k$  for enclosures without ventilation openings and with an effective cooling surface  $A_e \leq 1,25$  m<sup>2</sup>**

**Table 10 – Equation for Figure 7**

Variable	Algebraic expression
$k$	$k = 4$ if $(A_e < 0,08)$ else $0,626 \times (A_e)^{-0,737}$
<b>Key</b>	
$A_e$	effective cooling surface ( $m^2$ )
$k$	enclosure constant

**Key**

$g$  height/width factor (see 5.3.4)

$c$  temperature distribution factor

NOTE See Table 11 for the algebraic expressions related to the curve.

Boundary conditions: the factor  $g$  shall be equal or higher than 0 and not exceed 3.

**Figure 8 – Temperature distribution factor  $c$  for enclosures without ventilation openings and with an effective cooling surface  $A_e \leq 1,25 m^2$**

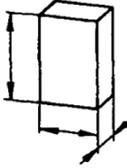
**Table 11 – Equation for Figure 8**

Variable	Algebraic expressions
<i>c</i>	If $g > 0,814\ 7$ , $c = 0,324\ 055 \times (1 - e^{(-1,882\ 7 \times g + 0,385\ 79)}) + 0,936\ 43$ Else, $c = 0,193\ 54 \times g + 1$
<b>Key</b> <i>c</i> temperature distribution factor <i>g</i> height / width factor	

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Calculation of temperature-rise of air inside enclosure				
Customer/plant				
Type of enclosure				
Relevant dimensions for temperature-rise	height	mm	Type of installation:	
	width	mm	Ventilation openings:    yes/no	
	depth	mm	Number of horizontal partitions:	

Effective cooling surface		Dimensions	$A_o$	Surface factor $b$ according to Table 3	$A_o \times b$ (column 3) × (column 4)
		m × m	m <sup>2</sup>		m <sup>2</sup>
		2	3		4
	Top				
	Front				
	Rear				
	Right-hand side				
$A_e = \Sigma(A_o \times b) = \text{Total}$					

With an effective cooling surface $A_e$	
Exceeding 1,25 m <sup>2</sup>	Not exceeding 1,25 m <sup>2</sup>
$f = \frac{h^{1,35}}{A_b}$ (see 5.3.4)	$g = \frac{k}{w}$ (see 5.3.4)
= _____ =	= _____ =

Air inlet openings	cm <sup>2</sup>	
Enclosure constant $k$		
Factor for horizontal partitions $d$		
Effective power loss $P$	W	
$p^x = P \dots$		
$\Delta t_{0,5} = k \times d \times p^x$	K	
Temperature distribution factor $c$		
$\Delta t_{1,0} = c \times \Delta t_{0,5}$	K	

Characteristic curve:

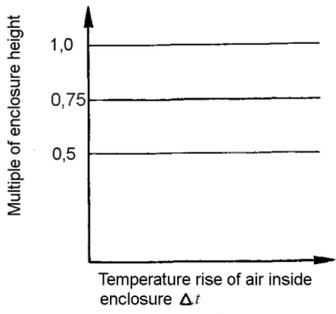


Figure 9 – Calculation of temperature-rise of air inside enclosures

## Annex A (informative)

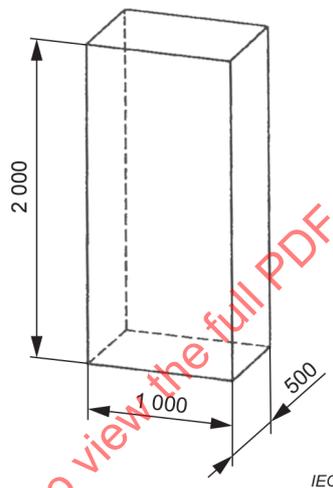
### Examples for the calculation of the temperature-rise of air inside enclosures

#### A.1 Example 1

Single enclosure with exposed side faces without ventilation openings and without internal horizontal partitions (see Figure A.1).

Effective power loss of equipment installed in the enclosure:  $P = 300 \text{ W}$ .

Dimensions in millimetres



**Figure A.1 – Example 1, calculation for an enclosure with exposed side faces  
without ventilation openings and without internal horizontal partitions**

*Calculation* (for values see template, Figure A.2 on Example 1):

- The effective cooling surface  $A_e$  is determined according to 5.3.2.  
The individual surfaces are calculated from the enclosure dimensions, and the surface factor  $b$  is taken from Table 3.
- The temperature-rise of air  $\Delta t_{0,5}$  is determined according to 5.3.3.  
Formula (2) from column 2 of Table 1:

$$\Delta t_{0,5} = k \times d \times P^x \tag{A.1}$$

Factor  $k$  according to column 7 of Table 1 with  $A_e > 1,25 \text{ m}^2$ , as shown in Figure 3:

$$\text{for } A_e = 6,64 \text{ m}^2: k = 0,129$$

Factor  $d$  according to column 8 of Table 1 with  $A_e > 1,25 \text{ m}^2$ , as specified in Table 4:

with number of horizontal partitions = 0:  $d = 1,0$

Effective power loss (as specified)  $P = 300 \text{ W}$ .

Exponent  $x$  from column 10 of Table 1 with  $A_e > 1,25 \text{ m}^2$ :  $x = 0,804$

With these values entered into the Formula (A.1), the following result is obtained:

$$\Delta t_{0,5} = k \times d \times P^x = 0,129 \times 1,0 \times 300^{0,804}$$

$$\Delta t_{0,5} = 12,63 \text{ K} \approx 12,6 \text{ K}$$

- The temperature-rise of air  $\Delta t_{1,0}$  is determined according to 5.3.4.

Formula (3) from column 3 of Table 1:

$$\Delta t_{1,0} = c \times \Delta t_{0,5} \quad (\text{A.2})$$

Factor  $c$  according to column 9 of Table 1 with  $A_e > 1,25 \text{ m}^2$ , as shown in Figure 4:

$$f = \frac{h^{1,35}}{A_b} = \frac{2,2^{1,35}}{1,0 \times 0,5} = 5,80$$

Curve 1 of Figure 4 follows:

$$c = 1,44$$

With this value entered into Formula (A.2), the following result is obtained:

$$\Delta t_{1,0} = c \times \Delta t_{0,5} = 1,44 \times 12,63 = 18,18 \text{ K} \approx 18,2 \text{ K}$$

- The temperature-rise characteristic curve is determined for enclosures with  $A_e > 1,25 \text{ m}^2$ , in accordance with 5.3.5.2 (see Figure A.2 in the template on Example 1).
- The evaluation of the design is made in accordance with Clause 7.

It shall be verified whether the equipment installed in the enclosure is capable of functioning satisfactorily at the specified currents and calculated temperature-rises, considering the ambient air temperature (see Note of Clause 1).

If this is not so, the parameters shall be changed and the calculation repeated.

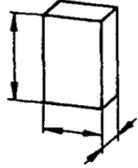
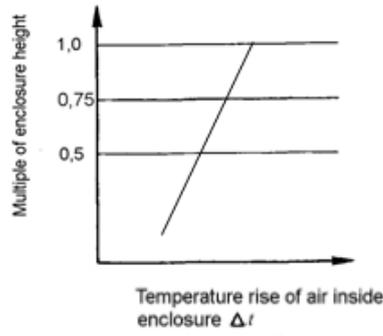
Calculation of temperature-rise of air inside enclosure					
Customer/plant <b>Example 1</b>					
Type of enclosure <b>Single enclosure</b>					
Relevant dimensions for temperature-rise	Height	<b>2 200</b>	mm	Type of installation: <b>Detached on all sides</b>	
	Width	<b>1 000</b>	mm	Ventilation openings: <b>yes/no</b>	
	Depth	<b>500</b>	mm	Number of horizontal partitions: <b>0</b>	
Effective cooling surface		Dimensions	$A_o$	Surface factor $b$ according to Table 3	$A_o \times b$ (column 3) $\times$ (column 4)
		m $\times$ m	m <sup>2</sup>		m <sup>2</sup>
		2	3	4	5
	Top	<b>1,0 <math>\times</math> 0,5</b>	<b>0,5</b>	<b>1,4</b>	<b>0,7</b>
	Front	<b>1,0 <math>\times</math> 2,2</b>	<b>2,2</b>	<b>0,9</b>	<b>1,98</b>
	Rear	<b>1,0 <math>\times</math> 2,2</b>	<b>2,2</b>	<b>0,9</b>	<b>1,98</b>
	Left-hand side	<b>0,5 <math>\times</math> 2,2</b>	<b>1,1</b>	<b>0,9</b>	<b>0,99</b>
	Right-hand side	<b>0,5 <math>\times</math> 2,2</b>	<b>1,1</b>	<b>0,9</b>	<b>0,99</b>
$A_e = \Sigma(A_o \times b) = \text{Total}$					<b>6,64</b>
With an effective cooling surface $A_e$					
Exceeding 1,25 m <sup>2</sup>			Not exceeding 1,25 m <sup>2</sup>		
$f = \frac{h^{1,35}}{A_b}$ (see 5.3.4)			$g = \frac{h}{w}$ (see 5.3.4)		
$= \frac{2,2^{1,35}}{1 \times 0,5} = 5,8$			$= \frac{\quad}{\quad} = \quad$		
Air inlet openings	cm <sup>2</sup>	<b>0</b>			
Enclosure constant $k$		<b>0,129</b>			
Factor for horizontal partitions $d$		<b>1</b>			
Effective power loss $P$	W	<b>300</b>			
$p^x = P \dots$		<b>98,09</b>			
$\Delta t_{0,5} = k \times d \times p^x$	K	<b>12,63 K <math>\approx</math> 12,6 K</b>			
Temperature distribution factor $c$		<b>1,44</b>			
$\Delta t_{1,0} = c \times \Delta t_{0,5}$	K	<b>18,18 K <math>\approx</math> 18,2 K</b>			
Characteristic curve:					
					

Figure A.2 – Example 1, calculation for a single enclosure

## A.2 Example 2

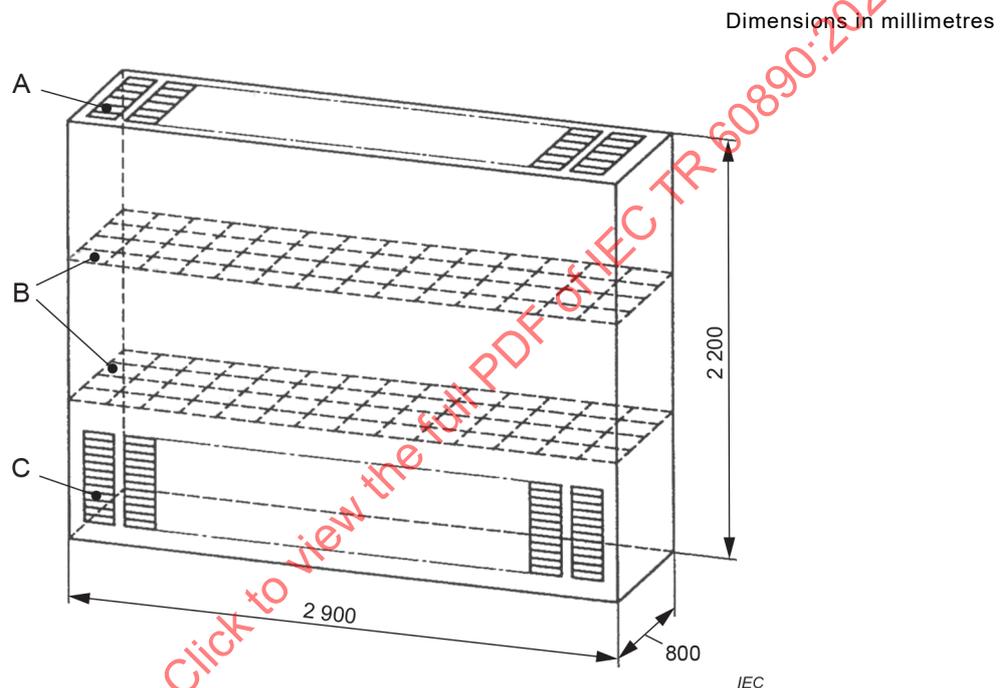
Enclosure for wall-mounting with ventilation openings

cross-section of air inlet openings = 1 220 cm<sup>2</sup>

cross-section of air outlet openings = 1 800 cm<sup>2</sup>

with two horizontal partitions inside the enclosure. Each horizontal partition, for example perforated plate, has ventilation openings, the cross-sectional areas of which exceed 50 % of the enclosure cross-section (see Figure A.3 and Figure A.4).

Effective power loss of equipment installed in the enclosure  $P = 2\,200\text{ W}$ .



### Key

- A Air outlet openings
- B Horizontal partitions with ventilation openings, for example perforated plate
- C Air inlet openings

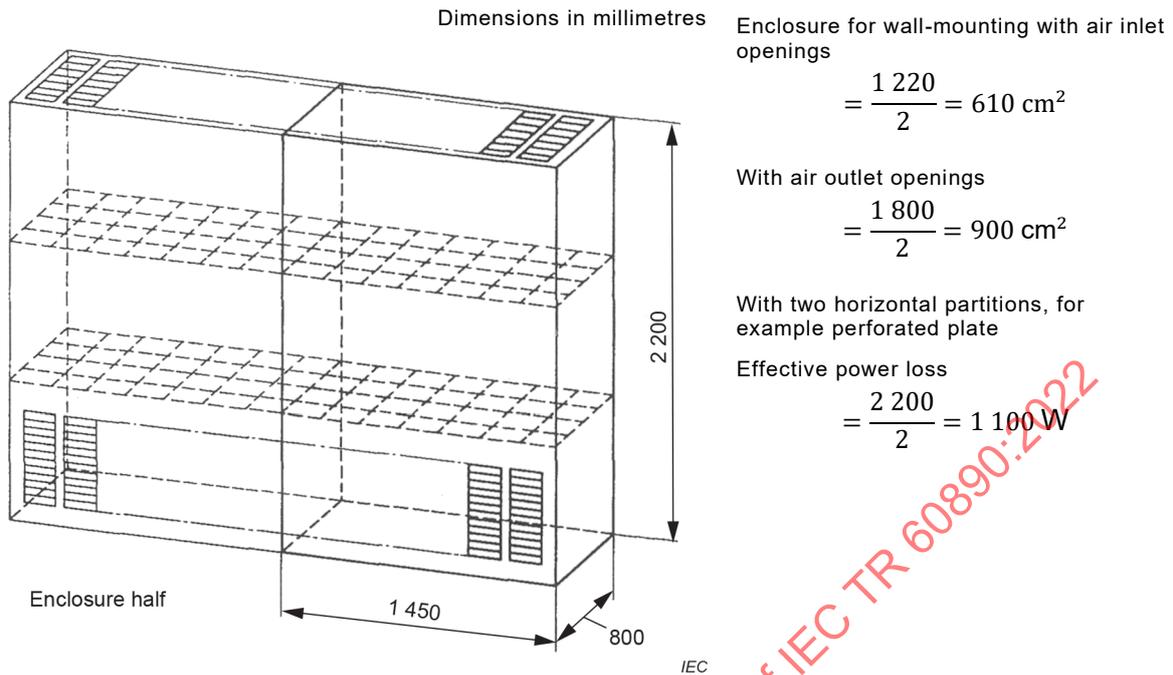
**Figure A.3 – Example 2, calculation for an enclosure for wall-mounting with ventilation openings**

Calculation (for values see template Figure A.5 on Example 2):

Given an expected cooling surface of the enclosure is more than 11,5 m<sup>2</sup> and has an enclosure width exceeding 1,5 m, the entire enclosure shall be divided, for calculation purposes, into sections (partial enclosures) as indicated in 5.3.1. To simplify the procedure, as no structural divisions are available, the entire enclosure is, in this example, divided into two equal sections (enclosure halves). The power losses and ventilation openings are supposed to be evenly distributed in both parts (enclosure halves) so that for the calculation they are divided by two.

The calculation is carried out for only one enclosure half, the result being applicable to the other half.

- Necessary information according to 5.2 for one half of the enclosure



**Figure A.4 – Example 2, calculation for one enclosure half**

- The effective cooling surface of each enclosure half is determined according to 5.3.2. The individual surfaces are calculated from the enclosure dimensions, and the surface factor *b* is taken from Table 3. The dividing surface between the two enclosure halves which has been obtained as a result of the fictitious division, is not taken into account in accordance with Table 3.
- The temperature-rise of air  $\Delta t_{0,5}$  is determined according to 5.3.3.

Formula (2) from column 2 of Table 1

$$\Delta t_{0,5} = k \times d \times P^x \tag{A.3}$$

Factor *k* according to column 7 of Table 1 and  $A_e > 1,25\ \text{m}^2$ , as shown in Figure 5.

For  $610\ \text{cm}^2$  air inlet openings and  $A_e = 7,674\ \text{m}^2$ :  $k = 0,071\ 3$

Factor *d* according to column 8 of Table 1 and  $A_e > 1,25\ \text{m}^2$  as specified in Table 5 with two horizontal partitions:  $d = 1,10$

Effective power loss (as specified)  $P = 1\ 100\ \text{W}$

Exponent *x* from column 10 of Table 1 with  $A_e > 1,25\ \text{m}^2$ :  $x = 0,715$

With these values entered into the above Formula (A.3), the following result is obtained:

$$\Delta t_{0,5} = k \times d \times P^x = 0,071 \times 1,10 \times 1\ 100^{0,715}$$

$$\Delta t_{0,5} = 11,72\ \text{K} \approx 11,7\ \text{K}$$

- The temperature-rise of air  $\Delta t_{1,0}$  is determined according to 5.3.4.

Formula (3) from column 3 of Table 1

$$\Delta t_{1,0} = c \times \Delta t_{0,5} \tag{A.4}$$

Factor  $c$  according to column 9 of Table 1 and  $A_e > 1,25 \text{ m}^2$ , as shown in Figure 6.

$$f = \frac{h^{1,35}}{A_b} = \frac{2,2^{1,35}}{1,45 \times 0,8} = 2,50$$

Figure 6 shows that, for  $610 \text{ cm}^2$  air inlet openings:

$$c = 1,88$$

With these values entered into Formula (A.4), the following result is obtained:

$$\Delta t_{1,0} = c \times \Delta t_{0,5} = 1,87 \times 11,67 = 22,03 \text{ K} \approx 22 \text{ K}$$

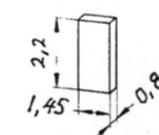
- The temperature-rise characteristic curve is determined for enclosures with  $A_e > 1,25 \text{ m}^2$ , in accordance with 5.3.5.2 (see Figure A.5 in the template on Example 2).
- The evaluation of the design is made in accordance with Clause 7.

It shall be verified whether the equipment installed in the enclosure is capable of functioning satisfactorily at the specified currents and calculated temperature-rises, considering the ambient air temperature (see Note of Clause 1).

If this is not so, the parameters shall be changed and the calculation repeated.

Calculation of temperature-rise of air inside enclosure

Customer/plant <b>Example 2</b>			
Type of enclosure <b>2 200 high, 2 900 wide, 800 deep; divided in 2 enclosure halves</b>			
Relevant dimensions for temperature-rise	Height	<b>2 200</b> mm	Type of installation: <b>Wall-mounting</b>
	Width	<b>1 450</b> mm	Ventilation openings: <b>yes/no</b>
	Depth	<b>800</b> mm	Number of horizontal partitions: <b>0</b>

Effective cooling surface		Dimensions	$A_o$	Surface factor $b$ according to Table 3	$A_o \times b$ (column 3) $\times$ (column 4)
		m $\times$ m	m <sup>2</sup>		m <sup>2</sup>
		2	3	4	5
Top		<b>1,45 <math>\times</math> 0,8</b>	<b>1,16</b>	<b>1,4</b>	<b>1,624</b>
Front		<b>1,45 <math>\times</math> 2,2</b>	<b>3,19</b>	<b>0,9</b>	<b>2,871</b>
Rear		<b>1,45 <math>\times</math> 2,2</b>	<b>3,19</b>	<b>0,5</b>	<b>1,595</b>
Left-hand side		<b>0,8 <math>\times</math> 2,2</b>	<b>1,76</b>	<b>0,0</b>	<b>-</b>
Right-hand side		<b>0,8 <math>\times</math> 2,2</b>	<b>1,76</b>	<b>0,9</b>	<b>1,584</b>
$A_e = \Sigma(A_o \times b) = \text{Total}$					<b>7,674</b>

With an effective cooling surface $A_e$	
Exceeding 1,25 m <sup>2</sup>	Not exceeding 1,25 m <sup>2</sup>
$f = \frac{h^{1,35}}{A_b} \text{ (see 5.3.4)}$ $= \frac{2,2^{1,35}}{1,45 \times 0,8} = 2,5$	$g = \frac{h}{w} \text{ (see 5.3.4)}$ $= \frac{2,2}{0,8} = 2,75$

Air inlet openings	cm <sup>2</sup>	<b>610</b>
Enclosure constant $k$		<b>0,071 3</b>
Factor for horizontal partitions $d$		<b>1,1</b>
Effective power loss $P$	W	<b>2 200/2 = 1 100</b>
$p^x = P \dots$		<b>149,48</b>
$\Delta t_{0,5} = k \times d \times p^x$	K	<b>11,72 K <math>\approx</math> 11,7 K</b>
Temperature distribution factor $c$		<b>1,88</b>
$\Delta t_{1,0} = c \times \Delta t_{0,5}$	K	<b>22,03 K <math>\approx</math> 22 K</b>

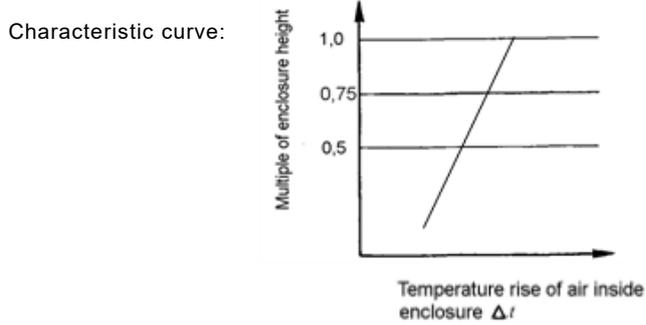


Figure A.5 – Example 2, calculation for an enclosure for wall-mounting with ventilation openings

## Annex B (informative)

### Guidance on the effects of an uneven power distribution

#### B.1 Horizontal partition

For typical assemblies used in the distribution of electrical energy, functional units are installed one above another with horizontal partitions in between each of the functional units. Typical arrangements are shown in the examples of Figure B.1



a) Assembly without ventilation openings, and less than 50 % perforation in horizontal partition

b) Assembly with ventilation openings, and at least 50 % perforation in horizontal partition

#### Key

1 to 5 horizontal separation

**Figure B.1 – Examples of assemblies with horizontal partitions**

The calculation method in Clause 5 assumes:

- 1) there is an approximately even power distribution within the assembly; and,
- 2) with a ventilated assembly, the area of the ventilation openings (perforation) in each horizontal partition is at least 50 % of the horizontal cross-section of the compartment to ensure a sufficient air flow through the compartment.

In some assemblies, for example certain designs of motor control centre (MCC), these conditions are not fulfilled; uneven power distribution can result from one circuit having a much higher power dissipation per unit volume (circuit with highest power dissipation) than the others and/or the perforation in horizontal partitions can be much less than 50 % of the horizontal cross section of the compartment.

#### B.2 Calculation of internal air temperature-rise for assemblies with ventilation openings with even power distribution and less than 50 % perforation in horizontal partitions

Assuming the power dissipation is approximately even within the section being considered, calculate the temperature-rise assuming there is no ventilation. The air temperature at any position within the section shall not exceed the maximum operating temperature allowed for the components at their respective positions within the section. See 5.4.

### B.3 Calculation of internal air temperature-rise with an uneven power distribution

This is a two or three step process.

- First step: determine the air temperature-rise at the point in the section where the higher-power dissipation circuit shall be located. This can be by measurement of the temperature in a reference design temperature-rise test. Alternatively, using this document calculate the air temperature-rise at the point in the section where the higher-power circuit shall be located considering the total power loss of the section, excluding the power loss of the higher-power circuit. For example,  $T^{\circ} D3$  in Figure B.2.
- Second step: assume the higher-power circuit (PW D3 in Figure B.2) is enclosed as it is within the assembly by using factors for covered surfaces in Table 3, and calculate the air temperature within PW D3 in accordance with 5.3, using the dimensions of PW D3 and assuming an ambient temperature  $T^{\circ} D3$ . The calculated air temperature within PW D3 shall not exceed the maximum operating temperature allowed for the components installed within PW D3. See 5.4.
- Third step: if the higher-power circuit is located at the top position, this step is not required. If the higher-power circuit is not located at the top of its section using 5.3, calculate the air temperature within the section considering the total power loss within the section. The calculated air temperature at any position within the section shall not exceed the maximum operating temperature allowed for the components at their respective positions. See 5.4.

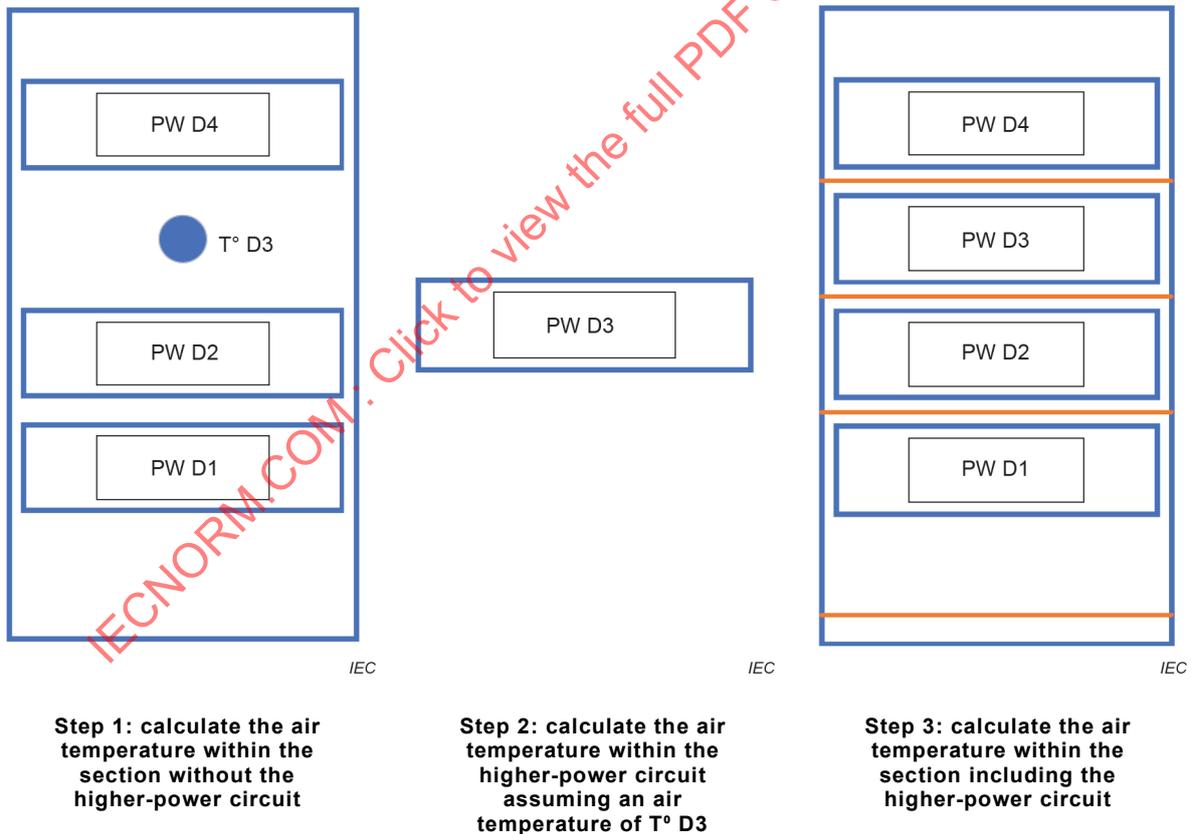


Figure B.2 – Temperature-rise verification of a higher-power circuit

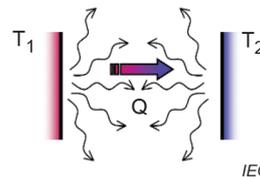
## Annex C (informative)

### Guidance on the additional temperature-rise effect due to solar radiation

#### C.1 General

In case of outdoor installation of the enclosure, and unless installed in the shade or covered e.g. by a canopy or roof, the solar radiation will create an additional increase of temperature in the enclosure. This Annex C proposes an explanation of thermal effects due to solar radiation and their consequences for the calculation of the internal air temperature.

#### C.2 Solar radiation phenomena



##### Key

- T1 temperature of solid emission (sun)
- T2 temperature of solid receptor (enclosure)
- Q energy transferred from highest to lowest temperature surfaces

**Figure C.1 – Solar radiation phenomena**

Radiation is an energy transfer between two entities separated by the atmosphere (see Figure C.1). The materials have the capability of absorbing or emitting photons (quantity of energy). This transfer is almost instantaneous and does not need a material support. On the absorbing side, a part of the radiated energy is usually converted into heat.

When an assembly is installed outdoor the enclosure surface can absorb solar radiation. The type of material of the enclosure surfaces, and more precisely the surface roughness and its colour, can influence the ratio of absorption of the radiated energy and thus the total amount of heat within the enclosure.

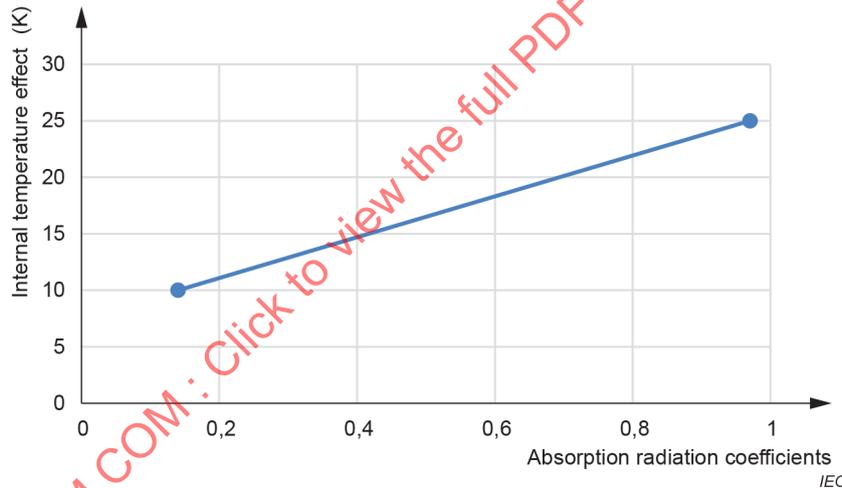
The exterior colour and finishing can have a huge impact on the absorption of solar radiation, described by the absorption coefficient. For enclosures in a black or dark colour, the absorption coefficient can be close to 1 and results in the maximum additional temperature-rise, compared to the same enclosure in a white colour, having a coefficient close to 0,1. Table C.1 below specifies different values of absorption coefficient, valid for solar radiation, but not for infrared, relating to the colour.

**Table C.1 – Approximate solar absorption radiation coefficients (according to colour)**

Colour	Approximate solar absorption radiation coefficients	Additional increase internal air calculation K
White	0,14	10
Cream	0,25	12
Yellow	0,3	12,9
Light grey, blue, green	0,5	16,5
Medium grey, blue, green	0,75	21
Dark grey, blue, green	0,95	24,4
Black	0,97	25

This table is from IEEE STD C37.24-2017.  
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A practical and linear approach can be used to convert and interpolate the influence of the difference between light and dark colours (see Figure C.2).



**Figure C.2 – Interpolation curve**

NOTE Manufacturers take into account aging of surfaces due to UV radiation when determining the absorption rate.

**C.3 Solar radiation – consequences for thermal calculation**

Due to the energy absorbed by the enclosure, the internal air temperature-rise increases in addition to the temperature-rise caused by internal power losses. Based on a ventilated metal enclosure test comparison and the technical approach documented in IEEE C37.24, an additional increase of 10 K shall be considered if the colour of the enclosure is a light colour or white. In case of grey or dark colours, the increase is higher and can reach 25 K.

To reduce or eliminate the effect of solar radiation on the temperature-rise inside an enclosure, manufacturers usually propose dedicated solutions and particular design by adding a special roof or a canopy. A canopy or roof should be sufficiently large to prevent direct sunlight shining on the assembly from mid-morning to mid- afternoon.

NOTE 1 Recommendations and explanations are mainly based on IEEE C37.24.

NOTE 2 For special installation conditions, e.g. for an indoor assembly installed at places exposed to skylight or to sources of heat radiation, a special agreement between user and manufacturer is defined. This can be taken into account e.g. by a special derating factor, derived from on-site test measurements.

#### **C.4 Solar radiation of enclosures with air ventilation openings**

The effect of solar radiation on the temperature-rise within an enclosure with air ventilation openings can be lower than within an enclosure without openings. If the increases on internal air temperature as defined in Table C.1 are not applied to an enclosure with air ventilation openings, it is the responsibility of the manufacturer of the assembly to provide relevant data.

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## Annex D (informative)

### Guidance on the effect of different enclosure materials, construction and finishes

#### D.1 General

The influence of the wall materials and thicknesses used for enclosures can have some effect on the internal steady state temperatures. For example, the thermal radiation effect is influenced by the type of coating whereas the thickness and material of the wall influence the thermal conduction and also the convection effect on the external surfaces.

#### D.2 Validity criteria

The generalised approach used in this method of calculation is applicable to enclosures made of metal (steel, aluminium, stainless steel) coated (both sides, inside and outside), insulating material like thermoplastic or thermoset or similar. Some explanations are given based on test results to ensure the validity of this assumption (see Clause D.3).

For bare steel, aluminium, or stainless steel enclosures (i.e. without a coating), due to the reduction of radiated thermal exchange, the calculation method of this document cannot be used. See Clause D.3 for an indication of the impact of using bare metal.

NOTE All types of paint as liquid, varnish, epoxy, and any colour can be considered as a coated surface. An anodised treatment of aluminium enclosures is also considered as a coated surface.

On special enclosures, like fire-resistant enclosures, the walls can include air gaps between the inner and outer surface (double wall enclosure) or a thermal insulating material. In that case, this document's method is not applicable without additional verification by test. The additional verification can be a comparison to provide a derating factor or an impact of the effective cooling surface of this special enclosure type.

#### D.3 Material of enclosure

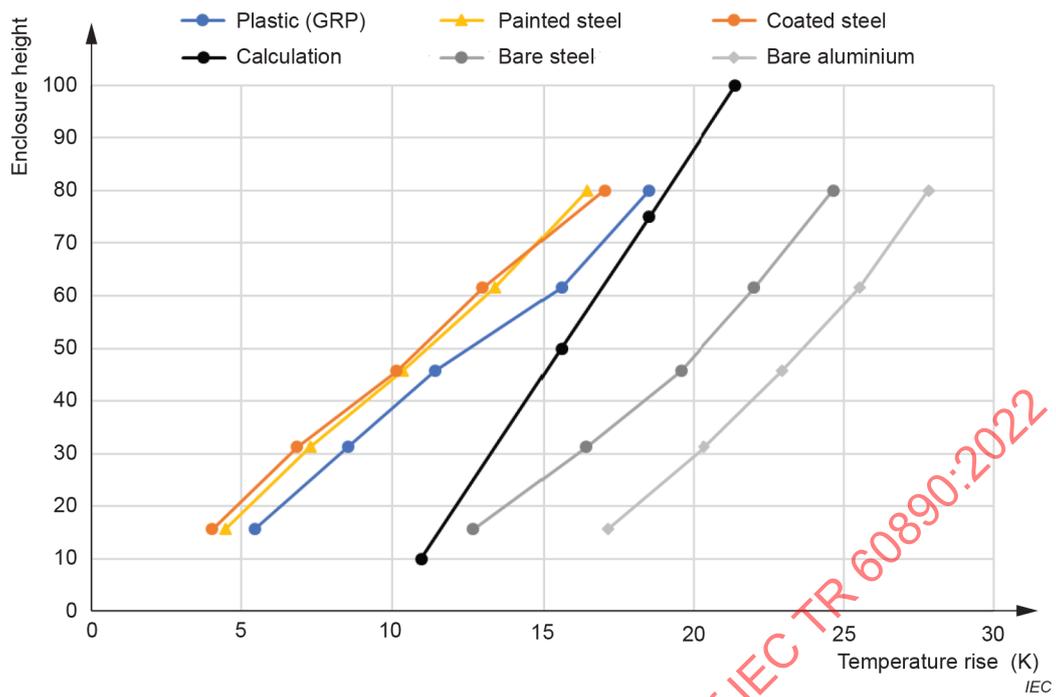
A thermoset enclosure, made of glass-fiber reinforced polyester, is compared with plastic coated and painted steel (RAL 7032, same colour as the thermoset enclosure).

All these tests have been conducted with heating resistors inside, supplying 90 W of simulated power losses almost evenly distributed within the enclosure, to maintain a temperature-rise of approximately 20 K on top ( $\Delta t_{1,0}$ ) of the enclosure. To eliminate natural ventilation effects, the enclosures have been selected or modified to fulfill IP6X.

Coated or painted metal enclosures show a similar thermal behavior to the plastic enclosure, slightly better though, by just of 2 K to 3 K, which is not deemed significant, since the measured values are less than the calculated values. The results obtain using bare enclosures are significantly different and it explains the scope of this document considering enclosures made of metal (steel, aluminum, stainless steel) coated (both sides, inside and outside), insulating materials like thermoplastic or thermoset or similar. The results are shown in Figure D.1.

#### D.4 Results

Results are stated in Figure D.1 below.



NOTE Curves in different colours are referring to different enclosure materials.

Figure D.1 – Results of comparison tests

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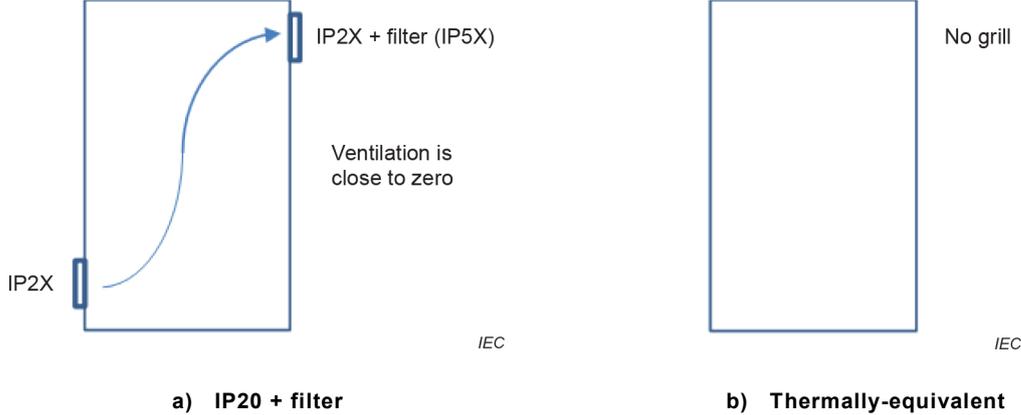


Figure E.2 – Effect of additional filters

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## **Annex F** (informative)

### **Guidance on forced ventilation management**

#### **F.1 General**

This type of thermal management generates a higher performance of air exchange compared to natural convection. Use of forced ventilation requires maintenance to ensure consistent performance during the whole life of the assembly. Details of the necessary maintenance shall be included in the documentation provided by the manufacturer of the assembly.

#### **F.2 Forced ventilation installation system**

The most common method of thermal management is using a fan. It is essential to take care how to select the correct fan. In most catalogues of thermal management system manufacturers or technical guides, fans are usually described by two different properties. The first-one is its performance in case of free air flow, and the second-one is given in case of working against a load, for example, a grille or an additional filter. This second value, which is the lower one, shall be used to select the correct fan.

Due consideration should be given to the fan supply characteristics, given for example that for different voltages and frequencies i.e. 50 Hz or 60 Hz the air flow rate of the same fan can vary.

A number of systems already exist, and some of them propose an additional monitoring system to prevent any risk of overheating due to the possible failure of the forced ventilation, e.g. because of a lack of maintenance of the filter.

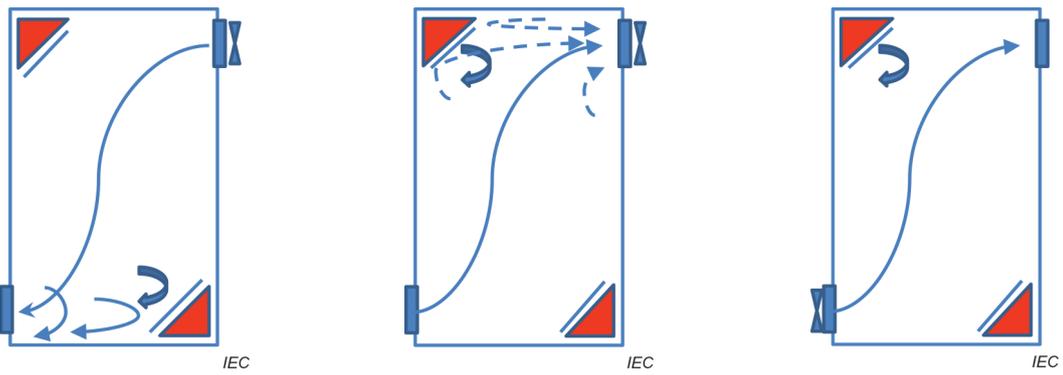
This document does not provide specific rules for incorporating forced ventilation into an assembly. Annex K provides some general guidance on determining the minimum airflow but as an alternative, the manufacturer of the assembly can use guidance from the cooling equipment manufacturer.

#### **F.3 Installation considerations**

Designers of assemblies using forced ventilation shall recognise there can be 'grey areas' within the assembly where the airflow is adversely affected by the forced cooling. The installation of temperature-critical devices within these spaces shall be avoided (see Figure F.1 a)).

The place of installation and the direction of the air flow, e.g. pushing air into or sucking air out of the enclosure, can lead to different results. In case of installing the fan at the top of the enclosure, to blow air out (see Figure F.1 b)), because the enclosures are usually not completely air-tight gaps or some small holes can modify the air-forced circulation. This effect can reduce the cooling in some areas of the enclosure (see Figure F.1 b)).

Another known consequence is that some polluted (unfiltered) air is drawn into the enclosure through these gaps. Based on those facts, the pushed-in air flow design with the fan placed at the bottom of the enclosure is the preferable solution in many cases (See Figure F.1 c)).



a) Top-fitted fan (1)

b) Top-fitted fan (2)

c) Bottom-fitted fan

**Key**

- Red-filled zone      "grey" area
- Solid arrow         air circulation
- Dashed arrow       gaps, holes additional air entrance
- Broad arrow         air re-circulation

**Figure F.1 – Examples of forced ventilation arrangements**

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## Annex G (informative)

### Power loss values calculation

#### G.1 General

The reliability of the thermal calculation is directly influenced by the accuracy of the power loss values used. It is important to take into account the most onerous configuration in operation mode including the power losses of the switching and isolating devices, electronic devices, cables, busbar(s), auxiliary power supply, etc.

#### G.2 Power losses of low-voltage switchgear and controlgear

In general, the device manufacturer is able to provide power loss values for their devices under specific conditions. Care should be taken to ensure the power loss values given apply to the arrangement being considered, for example power losses can be specified per pole when a three-pole device is being used. In addition, as the power losses are often current dependent, they shall be adjusted to determine the power losses under the normal operating conditions for the assembly. If this is not done, the total losses determined for the assembly can be higher than in practice and lead to oversizing the enclosure.

Examples of low-voltage switchgear and controlgear include switches, circuit-breakers, fuses, contactors, thermal relays and disconnectors. Some product standards for devices indicate how to determine the power losses giving a test method (see for example Annex G of IEC 60947-2:2016). In that case, power losses are usually given in the datasheet or catalogue. If the assembly incorporates devices where the power losses are not given, it is strongly recommended to ask the device manufacturer which value to use and if the losses are proportional to  $I^2$  or otherwise depending on the actual load.

Power losses that are representative for the actual conditions in operation shall be taken into account. The following conditions shall be considered. Unless otherwise stated or agreed between the manufacturer of the assembly and device manufacturer, power losses are considered to be measured:

- under full load conditions (e.g. at its rated current,  $I_n$  or  $I_e$ );
- with the device at steady-state temperature;
- with single or three phase supply used based on type of device;
- with the frequency representative of the end use condition.

#### G.3 Power losses of conductors connecting low-voltage switchgear and controlgear

The power losses of conductors (wires, cables, bars and similar) connecting switching devices inside the enclosure is a non-negligible part of the total power loss. Power loss calculation method for cables and wires is stated in Annex I and guidance to minimize additional power-loss is stated in Annex J. The power losses are proportional to the length of the cable/wire and the square of the actual current flowing through it.

In case of software usage, a detailed calculation can be easier and should use the lengths of the real configuration. All cables and wires shall be adjusted to the assigned current (rated current of the circuit) in any case.

#### **G.4 Power losses of busbars**

The power loss of connecting conductors of switching devices and the power loss of busbars (distribution and main busbar), if any, are part of the total power losses within an enclosure. Power losses are proportional to the length and the square of the actual current flowing through the busbar. The length of a multiphase busbar system can be considered for each configuration by taking into account the average length of the phases. The power losses shall be adjusted to the assigned current (rated current of the circuit).

Technical data to calculate the power losses of a busbar system can be found in DIN 43670 for aluminium busbar and DIN 43670-2 for hybrid busbar according to the same arrangement and current rating of Table I.3.

NOTE Manufacturers can provide specific values of power losses for their product range of busbars, taking into account the architecture, the material, and dynamic effects of the magnetic field in detail (e.g. by measurement).

#### **G.5 Power losses of electronic devices**

Some devices have independent power loss (i.e. which are not proportional to the square of the current), e.g. the coil of a contactor, or electronic devices as PLC modems, power supplies to electronic components. For all those components, the power losses shall be identified and added to the total losses for thermal calculation.

In relationship with the power losses, two types of electronic functions can be considered:

- non current-dependent, e.g. modems, communications devices, control units. In that case, only the power loss of the device shall be taken into account in the calculation. The power loss of cable and wire connections can be ignored;
- current-dependent, e.g. variable speed drives, motor-starters, dimmers according to the device manufacturer informations. For variable speed drives, see also power loss calculation in IEC 61800-9-2. In the case of current dependant devices, cables and wires connections shall be taken into account in the total power losses associated with these devices.

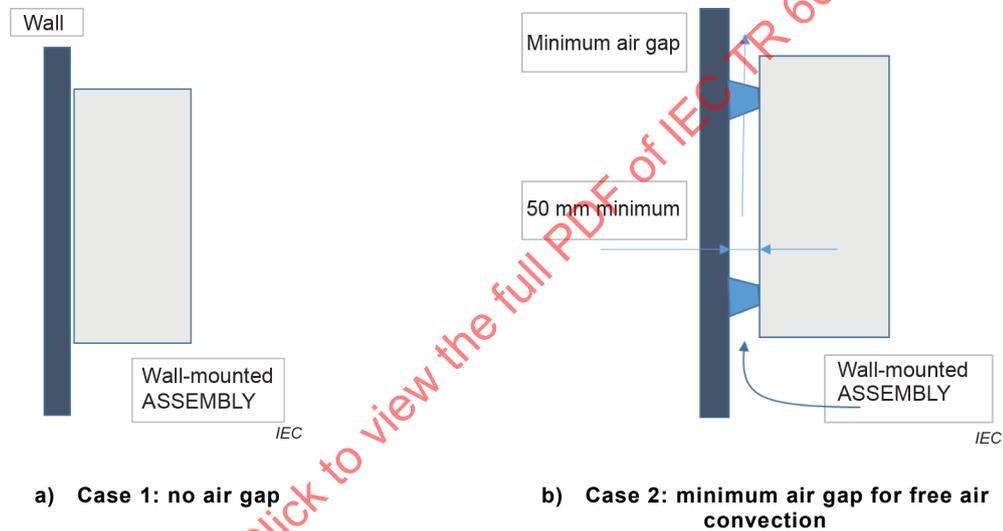
## Annex H (informative)

### Guidance on the impact of an adjacent wall on the assembly cooling surfaces

Wall-mounted and floor-standing installation of an enclosure on or near a wall reduces the active surface area of heat exchange between the enclosure and the ambient air. In case of wall-installation, an air gap of at least 50 mm between the wall and the enclosure is considered to allow a sufficient air convection (see Figure H.1). In this case, the thermal behaviour can be considered as in free air. See 5.3.2 for the effects of this installation factor.

NOTE 1 Assembly or enclosure manufacturers can provide different values of a minimum gap size in respect of tests, carried out to verify the effects.

NOTE 2 Manufacturer in its documentation define any limitations in respect of clearance between the top of the assembly and the room ceiling and/or air clearances at the sides of the assembly.



**Figure H.1 – Wall-mounted assembly**

In case of floor-standing assemblies of a width of up to 2 m, an air gap of > 50 mm between wall and enclosure shall be observed (see Figure H.2). In this case, the thermal behaviour can be considered as in free air. See 5.3.2 for the effects of this installation factor.

For assemblies of a width greater than 2 m, the assembly shall be considered as having:

- its back against the wall; or,
- a distance that is sufficient for the assembly to be considered as being in free air e.g. minimum 200 mm; or,
- a distance between the assembly and the wall, sufficient for the assembly to be considered as being in free air, based on tests.

This information shall be provided in the assembly manufacturer's documentation.

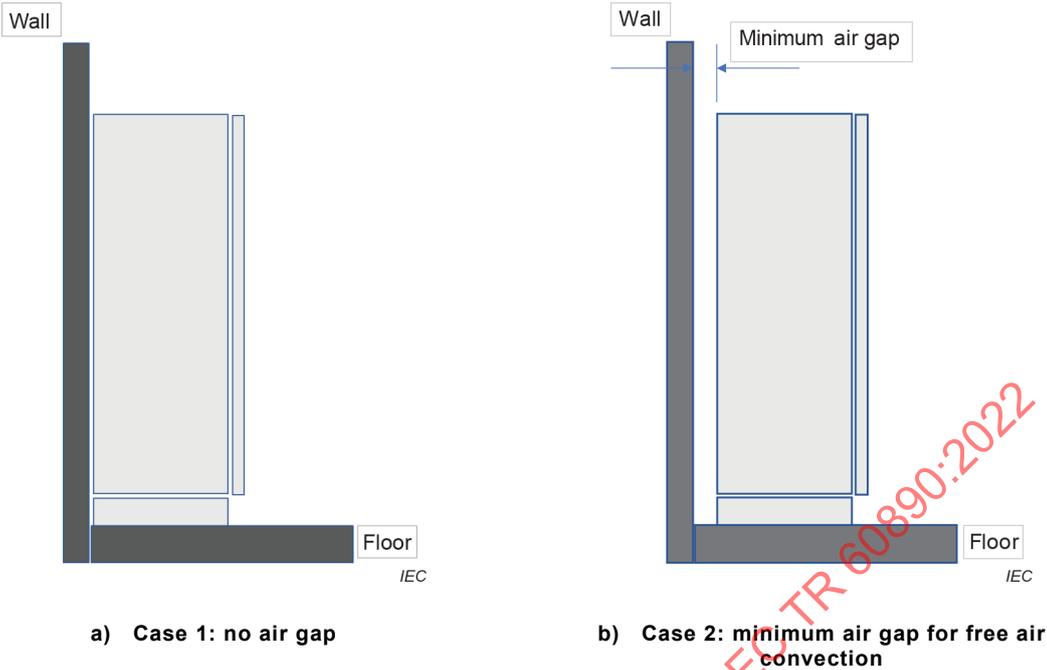


Figure H.2 – Floor-standing assembly

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